

Amendments to the Claims

1. **(Previously Presented)** A method for polishing an object by using an abrading surface made of abrasive particles and a binder, said method comprising:

polishing the object by the abrading surface while supplying a liquid not containing any abrasive particles for a determined time period; and

further polishing the object by the abrading surface while supplying abrasive particles so as to perform additional removal of a surface material to remove a specific film thickness.

2. **(Previously Presented)** A method according to claim 1, wherein said further polishing to remove the surface material is performed with the abrading surface by supplying a slurry containing abrasive particles to the abrading surface.

3. **(Previously Presented)** A method according to claim 1, wherein said further polishing to remove the surface material comprises:

polishing while concurrently dressing the abrading surface with a liquid not containing abrasive particles to thereby generate free abrasive particles therefrom.

4. **(Cancelled)**

5. **(Previously Presented)** A polishing apparatus for polishing a surface of an object, said polishing apparatus comprising:

a holder for holding the object;

an abrading surface comprising abrasive particles and a binder;

a mechanism for pressing the surface of the object to said abrading surface while producing a sliding motion over a polishing interface;

a device for supplying a liquid not containing abrasive particles to the polishing interface; and

a surface material removal device for performing additional material removal by supplying abrasive particles on said abrading surface, said surface material removal device being integrally mounted in said polishing apparatus.

6. **(Previously Presented)** A polishing apparatus according to claim 5, wherein said surface material removal device is a device for supplying a slurry containing abrasive particles to the polishing interface.

7. **(Previously Presented)** A polishing apparatus according to claim 5, wherein said surface material removal device is a device for dressing said abrading surface so as to release abrasive particles from said abrading surface.

8. **(Previously Presented)** A polishing apparatus according to claim 5, further comprising:
first polishing means for polishing while supplying a liquid not containing abrasive particles to the polishing interface; and
second polishing means for polishing while supplying a slurry containing abrasive particles to the polishing interface.

Claims 9-58 (Cancelled)

59. **(Currently Amended)** A method according to claim 54 for polishing an object using an abrading surface made of abrasive particles and a binder binding the abrasive particles, said method comprising:

dressing the abrading surface to shape the abrading surface by a dresser prior to a polishing process;

pressing the object against the abrading surface; and

polishing the object by making a sliding motion between a surface of the object and the abrading surface, wherein

said dressing process comprises removing residual particles from the dressed abrading surface.

said removing process comprises washing the abrading surface using a brush while flowing a liquid thereon, and

the dresser comprises diamond particles.

60. **(Previously Presented)** A method according to claim 59, wherein the dresser comprises the diamond particles electro-deposited in a nickel base.

Claims 61-73 **(Cancelled)**

74. **(Previously Presented)** A method for polishing an object using an abrading surface made of abrasive particles and a binder binding the abrasive particles, said method comprising:

polishing a surface of the object by pressing the object against the abrading surface and making a sliding motion between the surface of the object and the abrading surface; and

dressing the abrading surface by a dresser for roughening the abrading surface during said polishing process to generate free abrasive particles from the abrading surface,

wherein said polishing process comprises conducting a first stage polishing without dressing, and conducting a second stage polishing with dressing.

75. **(Cancelled)**

76. **(Previously Presented)** A method according to claim 74, wherein said polishing process is conducted while supplying a liquid not containing abrasive particles.

Claims 77-86 **(Cancelled)**

87. **(Currently Amended)** An apparatus according to claim 82 for polishing an object using an abrading surface made of abrasive particles and a binder binding the abrasive particles, said apparatus comprising:

a holder for holding the object;

a mechanism for pressing the object against the abrading surface and making a sliding motion between a surface of the object and the abrading surface;

a dresser for dressing the abrading surface prior to a polishing process to shape the abrading surface; and

a residual particles removing device for removing residual particles from the dressed abrading surface, wherein

said residual particles removing device comprises a brush for washing the abrading surface while flowing a liquid thereon, and

said dresser comprises diamond particles.

88. **(Previously Presented)** An apparatus according to claim 87, wherein said dresser comprises said diamond particles electro-deposited in a nickel base.

Claim 89-98 (Cancelled)

99. **(Previously Presented)** An apparatus for polishing an object using an abrading surface made of abrasive particles and a binder binding the abrasive particles, said apparatus comprising:

a holder for holding the object;

a mechanism for polishing a surface of the object by pressing the object against the abrading surface and making a sliding motion between a surface of the object and the abrading surface;

a dresser for dressing the abrading surface for roughening the abrading surface during the polishing process to generate free abrasive particles from the abrading surface; and

a controller for sending a signal for switching between a first stage polishing which is conducted without dressing, and a second stage polishing which is conducted with dressing.

100. (Cancelled)

101. **(Previously Presented)** An apparatus according to claim 99, wherein the polishing process is conducted while supplying a liquid not containing abrasive particles.

102. **(Previously Presented)** A method according to claim 1, wherein the object is a semiconductor wafer having a raised and depressed pattern thereon.

103. **(Previously Presented)** A method according to claim 1, wherein the object is held by a same holder during said polishing and said further polishing.

104. **(Original)** An apparatus according to claim 5, wherein said abrading surface comprises a surface of an abrading plate.

105. **(Previously Presented)** A method according to claim 74, wherein the dresser comprises a diamond dresser.

106. **(Previously Presented)** An apparatus according to claim 99, wherein the dresser comprises a diamond dresser.